



Group-Semi N/P-Channel Complementary MOSFET

Jul 2021

## GENERAL DESCRIPTION

The GSD4018DT uses advanced trench technology MOSFETs to provide excellent RDS(ON) and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications. Standard Product GSD4018DT is Pb-free. GSD4018DT is electrically identical.

## GENERAL FEATURES

### N-channel

- $V_{DS} = 40V, I_D = 10A$
- $R_{DS(ON)} < 23m\Omega @ V_{GS} = 10V$
- $R_{DS(ON)} < 30m\Omega @ V_{GS} = 4.5V$

### P-channel

- $V_{DS} = -40V, I_D = -10A$
- $R_{DS(ON)} < 45m\Omega @ V_{GS} = -10V$
- $R_{DS(ON)} < 50m\Omega @ V_{GS} = -4.5V$
- High density cell design for ultra low  $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high EAS
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

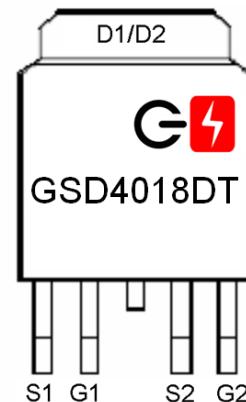
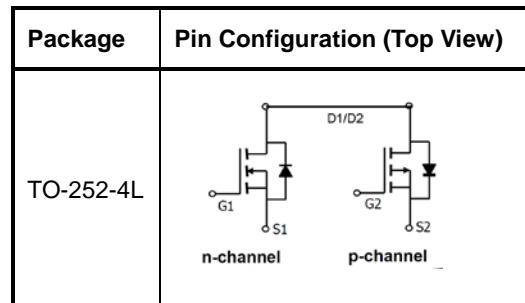
## Application

- H-bridge
- Inverters

**Absolute Maximum Ratings  $T_A = 25^\circ C$  unless otherwise noted**

Symbol	Parameter	Max N-channel	Max P-channel	Unit
$V_{DS}$	Drain-Source Voltage	40	-40	V
$I_D$	Drain Current -Continuous ( $TA = 25^\circ C$ ) -Continuous ( $TA = 70^\circ C$ )	12 8	-12 -8	A
$I_{DM}$	Drain Current - Pulsed (Note 1)	24	-24	A
$V_{GS}$	Gate-Source voltage	$\pm 20$	$\pm 20$	V
$I_{AS}$	Single Pulse Avalanche Current (Note 1)	14	24	A
$E_{AS}$	Single Pulse Avalanche Energy $L=0.1mH$ (Note 1)	18	36	mJ
$P_D$	Power Dissipation - $TA = 25^\circ C$ (Note 2) - $TA = 70^\circ C$	2	2	W
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	-55 to +150	°C

## PIN CONFIGURATION





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## Thermal Characteristics

Symbol	Parameter	GSD4018DT			Unit
$R_{\theta JA}$	Maximum Junction-to-Ambient, $t < 10s$	48			°C/W
	Maximum Junction-to-Ambient, Steady-State	74			°C/W
$R_{\theta JL}$	Maximum Junction-to-Lead, Steady-State	32			°C/W

## N-Channel Electrical Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						

BVDSS	Drain-Source Breakdown Voltage	VGS = 0V, ID = 250µA, TJ = 25°C	40	-	-	V
IDSS	Zero Gate Voltage Drain Current	VDS = 40V, VGS = 0V, -TJ = 55°C	-	-	1 5	µA µA
IGSSF	Gate-Body Leakage Current, Forward	VGS = 20V, VDS = 0V	-	-	100	nA
IGSSR	Gate-Body Leakage Current, Reverse	VGS = -20V, VDS = 0V	-	-	-100	nA

## On Characteristics

VGS(th)	Gate Threshold Voltage	VDS = VGS, ID = 250µA	1.0	1.8	3.0	V
RDS(on)	Static Drain-Source On-Resistance	VGS = 10V, ID = 6A VGS = 4.5V, ID = 5A	-	17 25	23 28	mΩ
gFS	Forward Transconductance	VDS = 5V, ID = 6A	-	20	-	S
Rg	Gate resistance	VGS=0V, VDS=0V, f=1MHz	-	3.2	-	Ω

## Dynamic Characteristics

Ciss	Input Capacitance	VDS = 20V, VGS = 0V, f=1MHz	-	516	-	pF
Coss	Output Capacitance		-	82	-	pF
Crss	Reverse Transfer Capacitance		-	43	-	pF

## Switching Characteristics

td(on)	Turn-On Delay Time	VDS = 20V, RG = 3Ω, ID = 6A , VGS = 10V (Note 5, 6)	-	6.4	-	ns
tr	Turn-On Rise Time		-	3.6	-	ns
td(off)	Turn-Off Delay Time		-	16.2	-	ns
tf	Turn-Off Fall Time		-	6.6	-	ns
Qg(10V)	Total Gate Charge	VDS = 20V, ID = 6A, VGS = 0~10V (Note 5, 6)	-	8.3	-	nC
Qg(4.5V)	Total Gate Charge		-	6.2	-	nC
Qgs	Gate-Source Charge		-	2.3	-	nC
Qgd	Gate-Drain Charge		-	1.6	-	nC

## Drain-Source Diode Characteristics and Maximum Ratings

IS	Maximum Continuous Drain-Source Diode Forward Current	-	-	25	A	
ISM	Maximum Pulsed Drain-Source Diode Forward Current	-	-	50	A	
VSD	Drain-Source Diode Forward Voltage	VGS = 0V, IS = 1A	-	0.7	1.0	V
trr	Reverse Recovery Time	VGS = 0V, IS = 12A dIF/dt = 100A/µs (Note 5)	-	8.5	-	ns
Qrr	Reverse Recovery Charge		-	2.2	-	nC



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## N-CHANNEL: TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

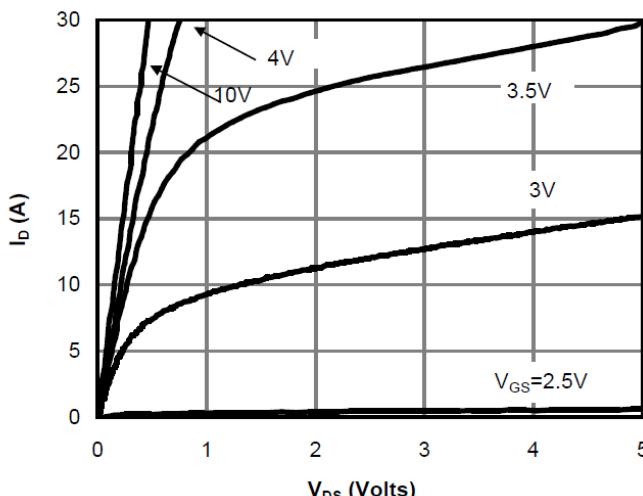


Fig 1: On-Region Characteristics (Note E)

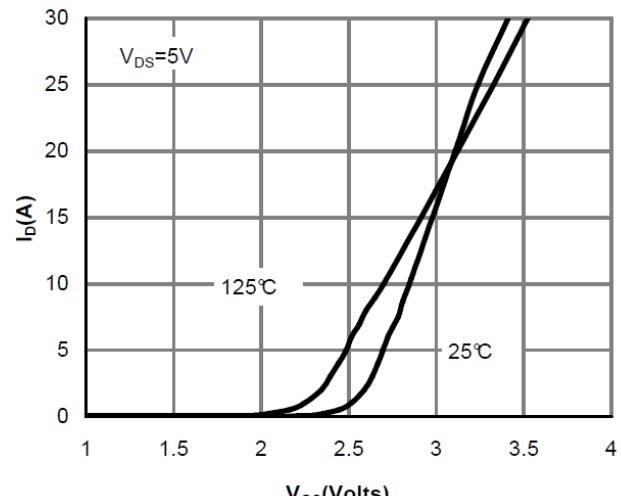


Figure 2: Transfer Characteristics (Note E)

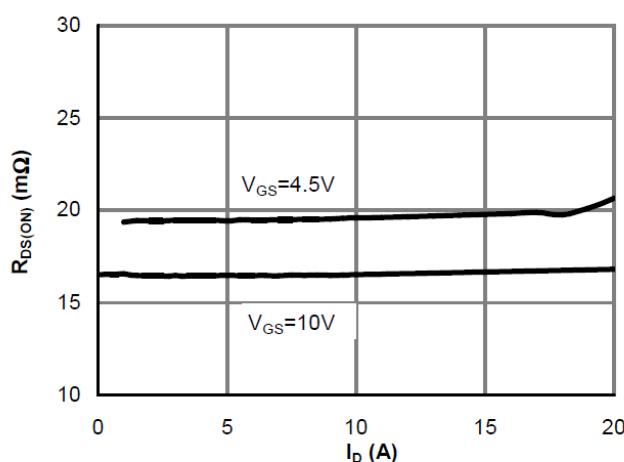


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

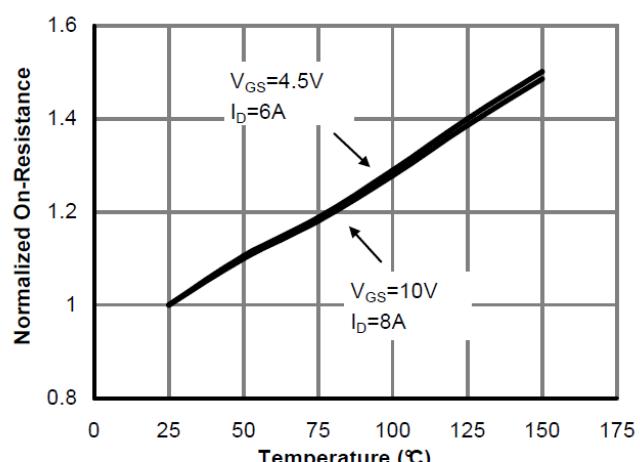


Figure 4: On-Resistance vs. Junction Temperature (Note E)

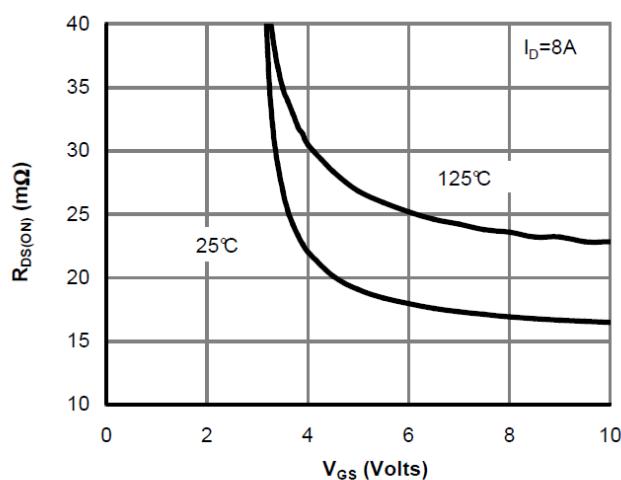


Figure 5: On-Resistance vs. Gate-Source Voltage (Note F)

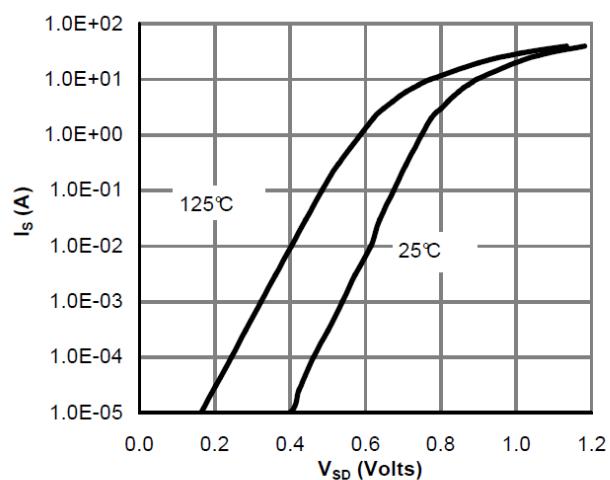


Figure 6: Body-Diode Characteristics (Note E)



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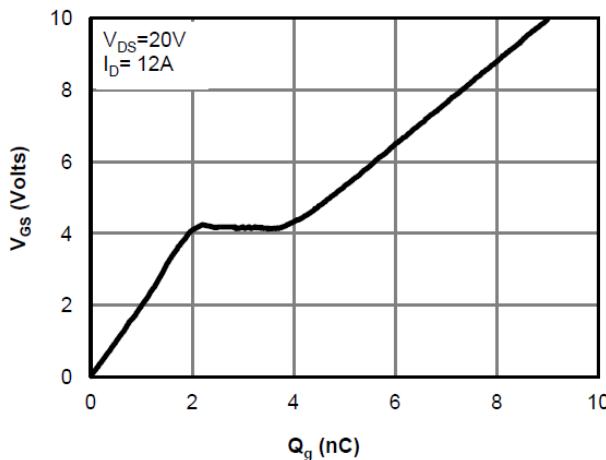


Figure 7: Gate-Charge Characteristics

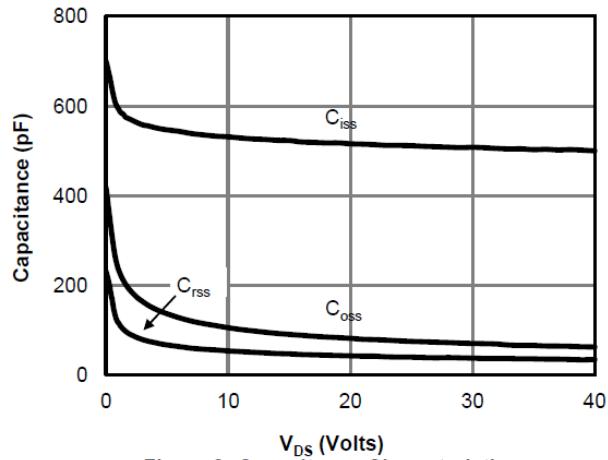


Figure 8: Capacitance Characteristics

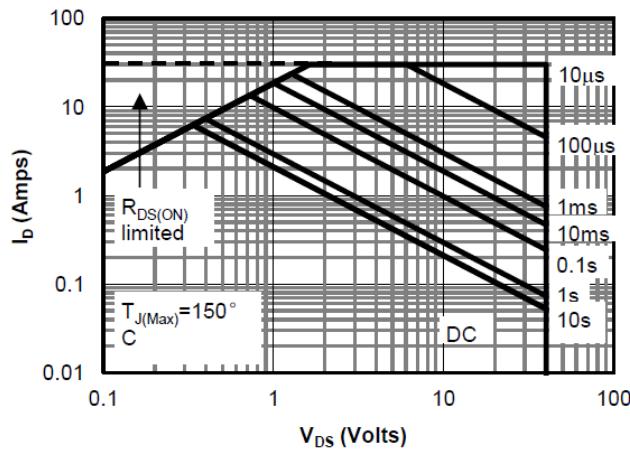


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

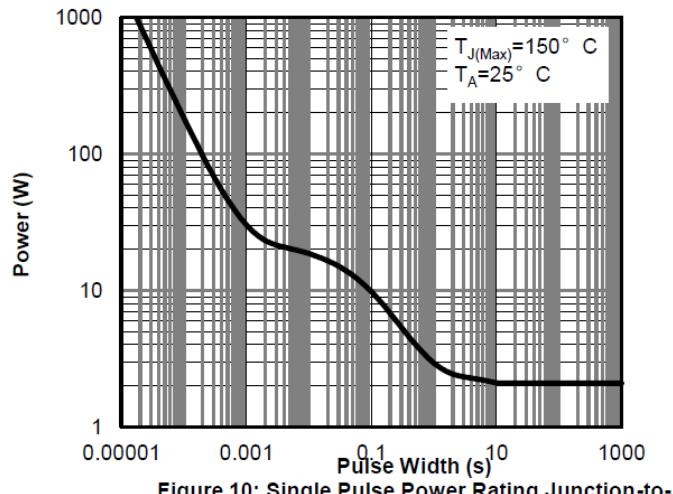


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

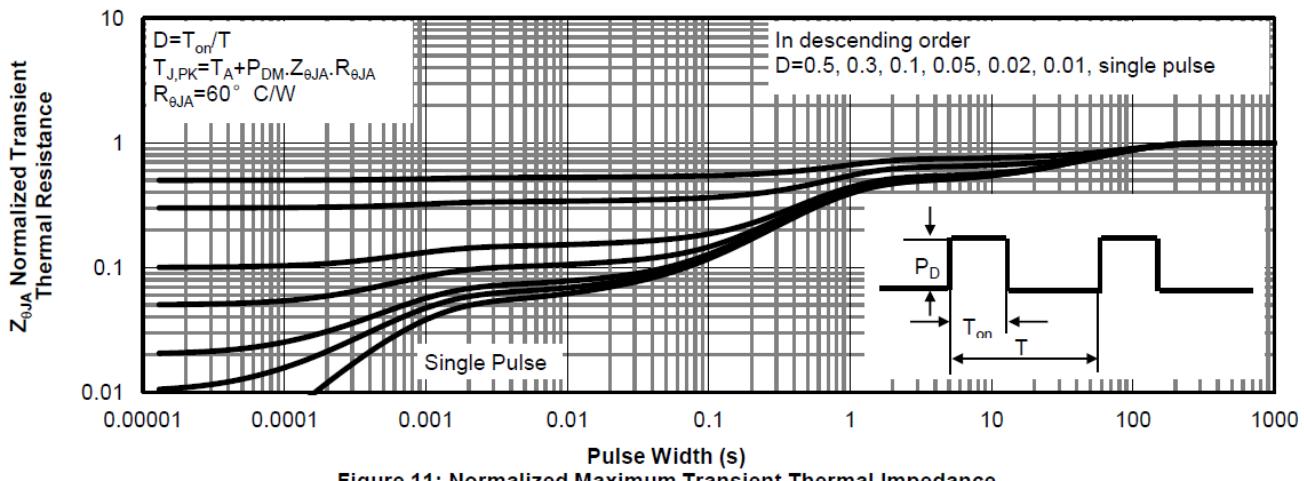


Figure 11: Normalized Maximum Transient Thermal Impedance



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## P-Channel Electrical Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
BVDSS	Drain-Source Breakdown Voltage	VGS = 0V, ID = -250µA, TJ = 25°C	-40	-	-	V
IDSS	Zero Gate Voltage Drain Current	VDS = -40V, VGS = 0V -TJ = 55°C	-	-	-1 -5	µA µA
IGSSF	Gate-Body Leakage Current, Forward	VGS = 12V, VDS = 0V	-	-	100	nA
IGSSR	Gate-Body Leakage Current, Reverse	VGS = -12V, VDS = 0V	-	-	-100	nA
<b>On Characteristics</b>						
VGS(th)	Gate Threshold Voltage	VDS = VGS, ID = 250µA	-1.0	-1.8	-3.0	V
RDS(on)	Static Drain-Source On-Resistance	VGS = -10V, ID = -6A VGS = -4.5V, ID = -5A	-	40 45	45 50	mΩ
gFS	Forward Transconductance	VDS = -5V, ID = -6A	-	20	-	S
Rg	Gate resistance	VGS=0V, VDS=0V, f=1MHz	-	3.2	-	Ω
<b>Dynamic Characteristics</b>						
Ciss	Input Capacitance	VDS = -20V, VGS = 0V, f=1MHz	-	1400	-	pF
Coss	Output Capacitance		-	200	-	pF
Crss	Reverse Transfer Capacitance		-	125	-	pF
<b>Switching Characteristics</b>						
td(on)	Turn-On Delay Time	VDS = -20V, RG = 3Ω, ID = -6A , VGS = -10V (Note 5, 6)	-	10	-	ns
tr	Turn-On Rise Time		-	31	-	ns
td(off)	Turn-Off Delay Time		-	24	-	ns
tf	Turn-Off Fall Time		-	28	-	ns
Qg(10V)	Total Gate Charge	VDS = -20V, ID = -6A, VGS = -0~10V (Note 5, 6)	-	18	-	nC
Qg(4.5V)	Total Gate Charge		-	14	-	nC
Qgs	Gate-Source Charge		-	3.2	-	nC
Qgd	Gate-Drain Charge		-	4.4	-	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
IS	Maximum Continuous Drain-Source Diode Forward Current	-	-	-	-	A
ISM	Maximum Pulsed Drain-Source Diode Forward Current	-	-	-	-25	A
VSD	Drain-Source Diode Forward Voltage	VGS = 0V, IS = -1A	-	-0.7	-1.2	V
trr	Reverse Recovery Time	VGS = 0V, IS = -12A dIF/dt = -100A/µs (Note 5)	-	24	-	ns
Qrr	Reverse Recovery Charge		-	30	-	nC



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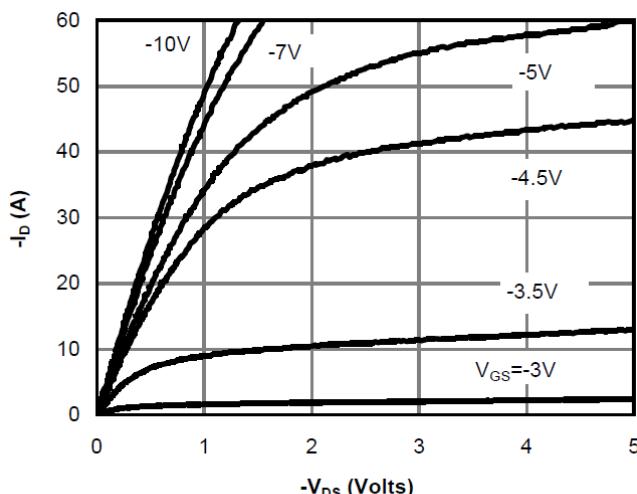


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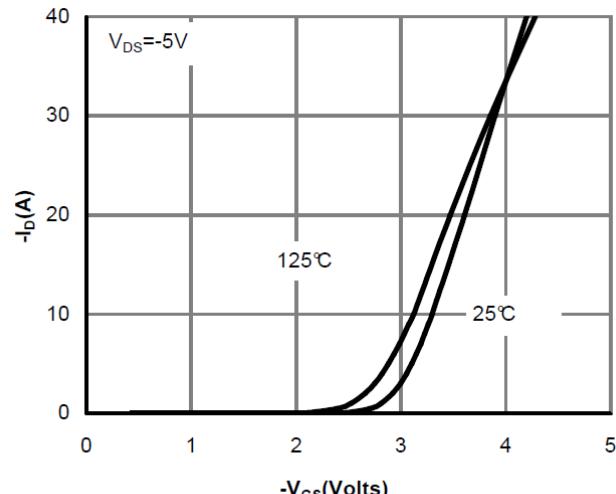


Figure 2: Transfer Characteristics (Note E)

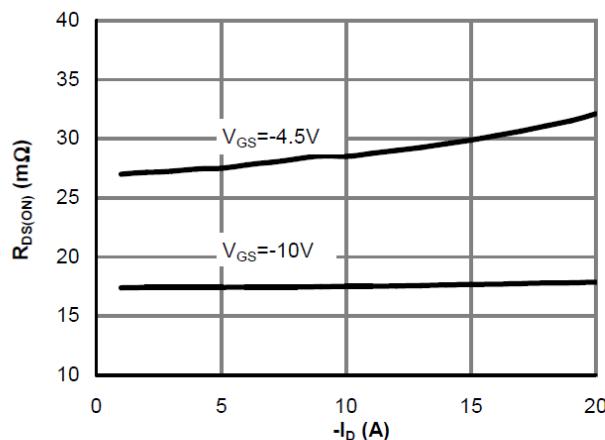


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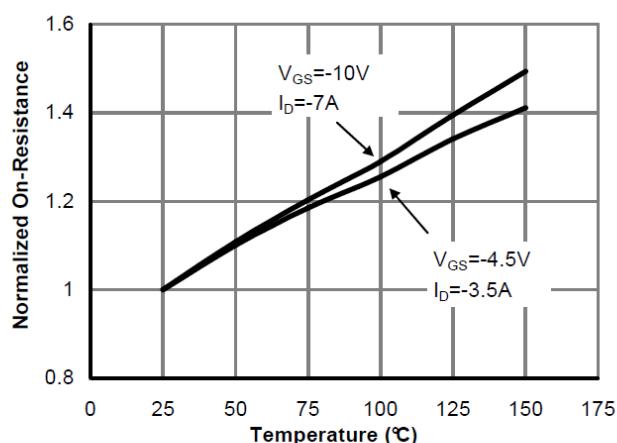


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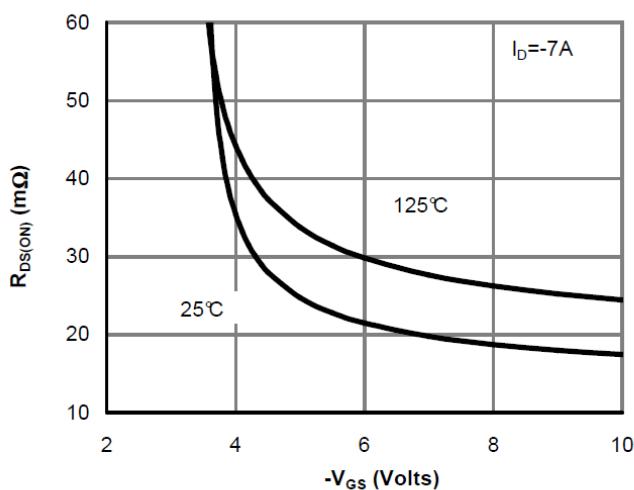


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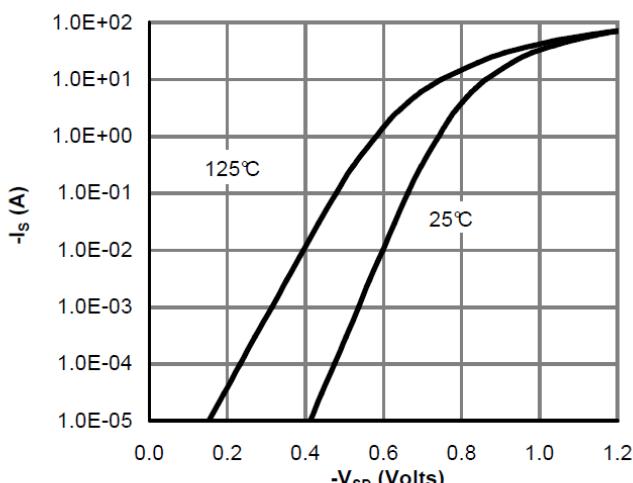


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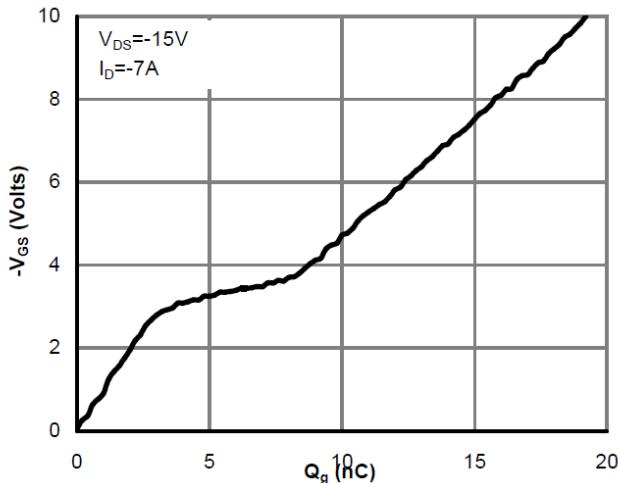


Figure 7: Gate-Charge Characteristics

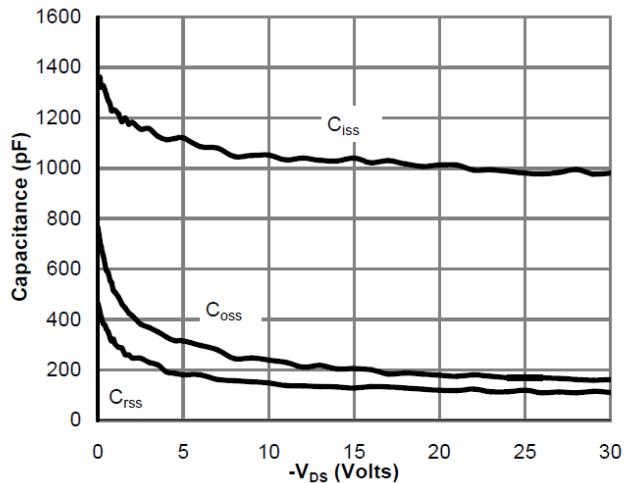


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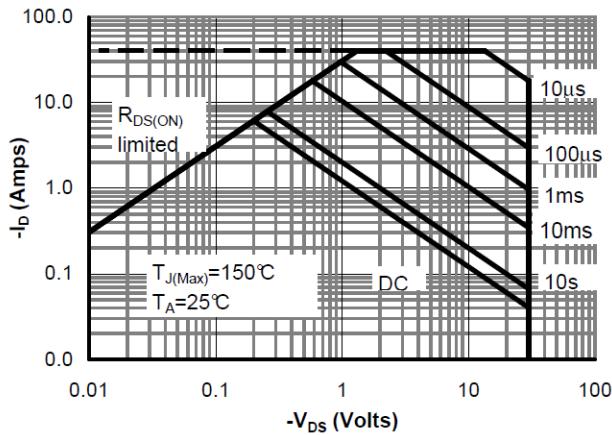


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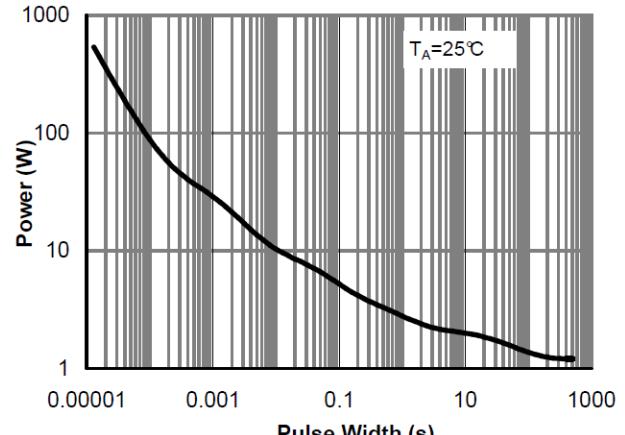


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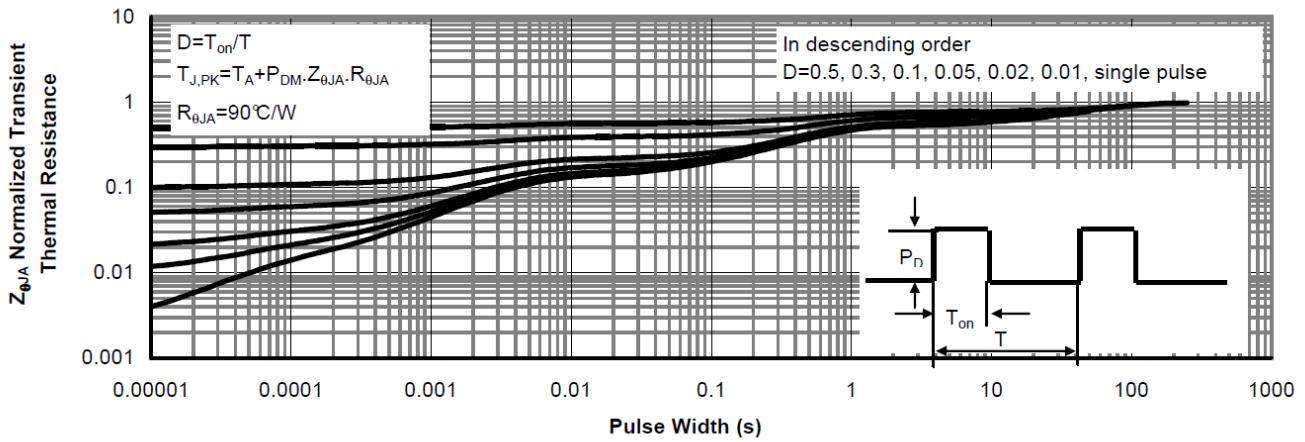


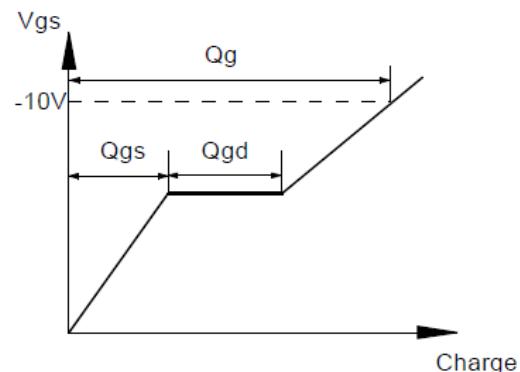
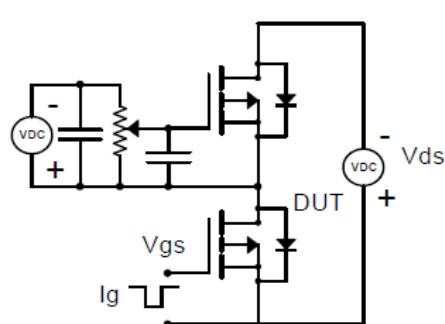
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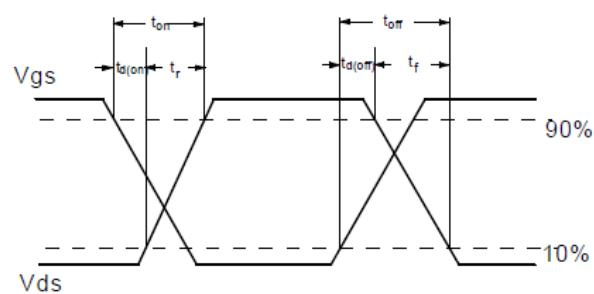
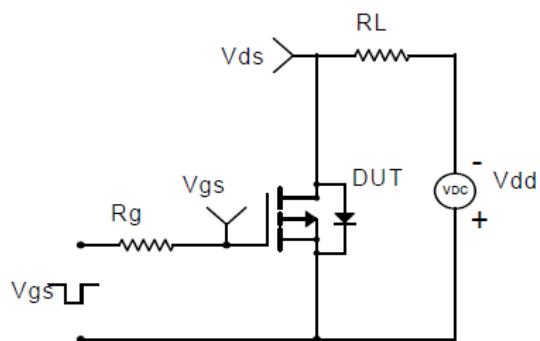
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Gate Charge Test Circuit &amp; Waveform



Resistive Switching Test Circuit &amp; Waveforms



Diode Recovery Test Circuit &amp; Waveforms

